



OLED SPECIFICATION

Model No:

REX009664ABPP3N00000

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
		11.00	

Release DATE:



1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2013/09/13		First release
Α	2014/06/25		Update Rev.
В	2015/02/09		Modify the height of
			module.
С	2015/12/08		Modify Life Time
D	2016/06/01		Modify Static
			electricity test



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1.General Specification

The Features is described as follow:

■ Module dimension: 24.9 × 22.95 × 1.65 mm

■ Active area: 19.946 × 13.418mm

■ Dot Matrix: 96*64

Dot size: 0.186 × 0.188 mmDot pitch: 0.208 × 0.21 mm

Display Mode: Passive Matrix

■ Duty: 1/64 Duty

Display Color: OLED , BlueController IC: SSD1305Z



2.Module Coding System

1	2	3	4	5	6	7	8	9	10	11	12	13
R	Е	Х	009664	Α	В	Р	Р	3	N	0	0	000

Item	Description		
1	R: Raystar Optron	ics Inc.	
2	E: OLED		
3	Display Type: C→C	Character Type, G→Graphic Ty	rpe,T→TAB Type ,X→COG Type
4	Dot Matrix: 96* 6	4	
5	Serials code		
		A: Amber	R: RED
	Franktin ar Calar	B: Blue	Y: Yellow
6	Emitting Color	G: Green	W : White
		S : Sky Blue	
7	Polarizer	P: With Polarizer; N: Withou	t Polarizer
8	Display Mode	P: Passive Matrix; A: Active	Matrix
9	Driver Voltage	3: 3.0 V; 5: 5.0V	
10	Touch Panel	N: Without touch panel; T: W	ith touch panel
10	Toucht anei	S: Resistive touch panel	
11	Products type	0:Standard type 1: Sunlight Readable type 2:Transparent OLED (TOLED 3:Flexible OLED 4:OLED for Lighting	
12	Product grades	0 : Standard(A-level) 2: B-level 3: C-level 1: high class(AA-level) Y: Consumer product	
13	Serial No.	Application serial number (000	0~ZZZ)





3.Interface Pin Function

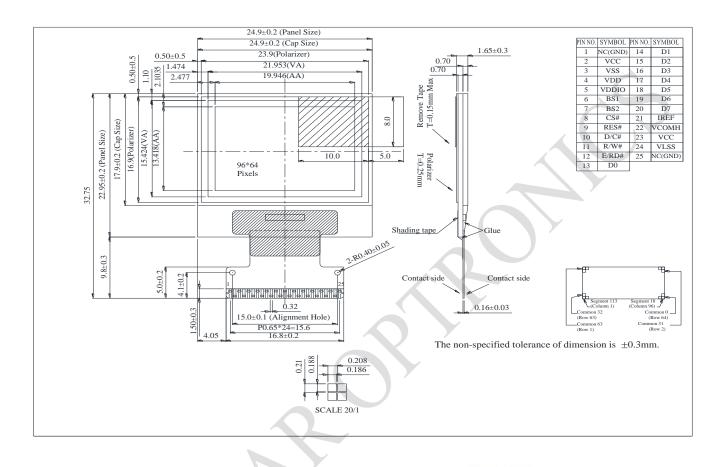
Pin Number	Symbol	I/O	Function
1.	N.C. (GND)	-	Reserved Pin(Supporting Pin) The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground.
2.	VCC	Р	Power Supply for OLED Panel This is the most positive voltage supply pin of the chip.lt must be supplied externally.
3.	VSS	Р	Ground of Logic Circuit This is a ground pin. It also acts as a reference for the logic pins. It must be connected to external ground.
4.	VDD	Р	Power Supply for Logic Circuit This is a voltage supply pin. It must be connected to external source.
5.	VDDIO	Р	Power supply for interface logic level. It should be match with MCU interface voltage level. VDDIO must always be equal or lower than VDD.
6.	BS1		Communicating Protocol Select These pins are MCU interface selection input. See the following table:
7.	BS2	I	
8.	CS#	Į	Chip Select This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low.
9.	RES#		Power Reset for Controller and Driver This pin is reset signal input. When the pin is low, initialization of the chip is executed.
10.	D/C#	1	Data/ Command Control This pin is Data/Command control pin. When the pin is pulled high, the input at D7~D0 is treated as display data. When the pin is pulled low, the input at D7~D0 will be transferred to the command register. For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams. When the pin is pulled high and serial interface mode is selected, the data at SDIN is treated as data. When it is pulled low, the data at SDIN will be transferred to the command register. In I2C mode, this pin acts as SA0 for slave address selection.
11.	R/W#	I	Read/ Write Selector Write This pin is MCU interface input. When interfacing to a68XX-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Pull this pin to "High" for read mode and pull it to "Low" for write mode.



			When 80XXinterface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled low and the CS# is pulled low.
12.	E/RD#	I	Read/Write Enable or Read This pin is MCU interface input. When interfacing to a68XX-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled high and the CS# is pulled low. When connecting to an 80XX-microprocessor, this pin receives the Read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low.
13.			
14.			Host Data In put/ Output Bus
15.			These pins are 8-bit bi-directional data bus to be connected to the
16.	D0~D7	1/0	microprocessor's data bus. When serial mode is selected, D1 will be
17.	וט~טו	I/O	the serial data input SDIN and D0 will be the serial clock input SCLK.
18.	=		When I2Cmode is selected, D2 & D1 should be tired together and serve as SDAout & SDAin in application and D0 is the serial clock
19.	-		input SCL.
20.	-		input SCL.
21.	IREF	I	Current Reference for Brightness Adjustment This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current lower than 10µA.
22.	VCOMH	0	Voltage Output High Level for COM Signal This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and VSS.
23.	VCC	Р	Power Supply for OLED Panel This is the most positive voltage supply pin of the chip.It must be supplied externally.
24.	VLSS	P	Ground of Analog Circuit This is an analog ground pin. It should be connected to VSS externally.
25.	N.C. (GND)		Reserved Pin(Supporting Pin) The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground.



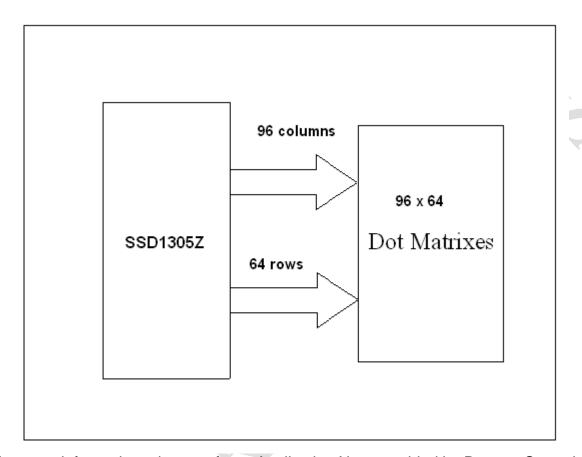
4. Counter Drawing & Block Diagram







FUNCTION BLOCK DIAGRAM



^{*}For more information, please refer to Application Note provided by Raystar Optronics.



5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1, 2
Supply Voltage for Display	VCC	0	15	V	1, 2
Operating Temperature	TOP	-40	+80	°C	-
Storage Temperature	TSTG	-40	+80	°C	, -

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate

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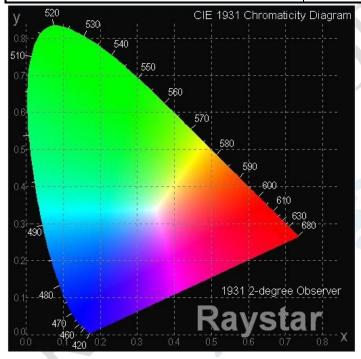
6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	_	10	12	15	V
Input High Volt.	VIH	_	0.8×VDD	^	VDDIO	V
Input Low Volt.	VIL	_	0	-	0.2×VDD	V
Output High Volt.	VOH	_	0.9×VDD	->	VDDIO	V
Output Low Volt.	VOL	_	0	<u></u>	0.1×VDD	V
50% Check Board operating Current	ICC	VCC=12V	7	8	10	mA



7. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	_	160	_	_	deg
view / trigic	(Η)φ	_	160	_	-	deg
Contrast Ratio	CR	Dark	2000:1	-		
Response Time	T rise	_	_	10		μs
Tresponde Time	T fall	_	_	10		μs
Display with 50% check E	Board Brightness		60	80	_	cd/m2
CIEx(Blue)		(CIE1931)	0.12	0.16	0.20	_
CIEy(Blue)		(CIE1931)	0.19	0.23	0.27	_





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8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	20,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.





9.Reliability

Content of Reliability Test

Environmenta	l Test			
Test Item	Content of Test	Test Condition	Applicable Standard	
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 240hrs	-,(
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	$\overline{}$	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80℃ 240hrs	7	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40℃ 240hrs	_	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60℃,90%RH 240hrs		
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40°C/80°C 100 cycles		
Mechanical Tes	st			
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	53	
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	-0	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs		
Others	100			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	1300	



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

NO	Item	Criterion			AQL			
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 			0.65			
02	Black or white spots on OLED (display only)	2.1 White and black spots of three white or black spots procedured 2.2 Densely spaced: No modern and the spots of three white and black spots of three white spots o		pres	ent.	() Y		2.5
03	OLED black spots, white spots, contamina tion (non-display)	3.1 Round type following drawing Φ=(x+y)/2			SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable TY Accept no dense 2	e Q	
		3.2 Line type : (A	As followin	g dr	awing)			0
			Length		dth	Acceptable C	Q TY	
	4	→ /¥ w	-4	_	≦0.02	Accept no de		
		→	L≦3.0	0.0	02 <w≦0.03< td=""><td>2</td><td></td><td>2.5</td></w≦0.03<>	2		2.5
		i.	L≦2.5	0.0	03 <w≦0.05< td=""><td>2</td><td></td><td></td></w≦0.05<>	2		
				0.0)5 <w< td=""><td>As round typ</td><td>е</td><td></td></w<>	As round typ	е	
04	Polarizer							
	bubbles	If bubbles are vis		Si	ze Ф	Acceptable 0	Q TY	
		judge using blac	•	Φ	≦0.20	Accept no de		
		specifications, not easy to find, must check in specify direction.		0.2	20<Φ≦0.50	3		2.5
				0.	50<Φ≦1.00	2	259	06
				1.0	00<Ф	0		
				То	tal Q TY	3		



NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination			
			y: Chip width z: 0 t: Glass thickness a: yth:		
		6.1 General glass chi 6.1.1 Chip on panel s		ween panels:	
		z: Chip thickness	y: Chip width	x: Chip length	
06	Chipped	Z≦1/2t	Not over viewing area	x≦1/8a	2.5
	glass	1/2t < z ≤ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or mo	ore chips, x is total len	igth of each chip.	
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x≦1/8a	
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more chips, x is the total length of each chip.			



NO	Item	Criterion	AQL
		Symbols:	
		x: Chip length y: Chip width z: Chip thickness	
		k: Seal width t: Glass thickness a: OLED side length	
		L: Electrode pad length	
		6.2 Protrusion over terminal :	
		6.2.1 Chip on electrode pad :	
			/
		Z	
		NA NA	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5$ mm $x \le 1/8$ a $0 < z \le t$	
		6.2.2 Non-conductive portion:	
		سأنهم أسا	
	Glass		
06	crack		2.5
	Clack	y \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
		X	
		y: Chip width x: Chip length z: Chip	
		thickness	
		$y \le L$ $x \le 1/8a$ $0 < z \le t$	
		⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO	
		must remain and be inspected according to electrode terminal	2
		specifications.	
		⊙If the product will be heat sealed by the customer, the alignment	
		mark not be damaged.	
		6.2.3 Substrate protuberance and internal crack.	
		y: width x: length	
		y ≤ 1/3L	
		y and the second	
			000
			-00



NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 2.5 0.65 2.5 2.5 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65



NO	Item	Criterion	AQL
12	General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65



Check Item	Classification	Criteria			
No Display	Major				
Missing Line	Major				
Pixel Short	Major				
Darker Short	Major				
Wrong Display	Major				
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Fixel C Light Fixel			



11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) Raystar has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)

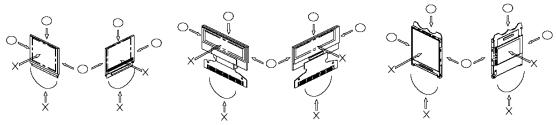
11.1 Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.





- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Raystar Optronics Inc. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.



11.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.



Page: 1

Module Sample Estimate Feedback Sheet				
Module Number:				
1 · Panel Specification :				
1. Panel Type:	□ Pass	□NG ,		
2. Numbers of Pixel:	□ Pass	□NG ,		
3. View Area:	□ Pass	□NG ,		
4. Active Area:	□ Pass	□NG ,		
5.Emitting Color:	□ Pass	□NG ,		
6.Uniformity:	□Pass	□NG ,		
7.Operating	□ Pass	□NG ,		
Temperature :				
8.Storage Temperature:	□ Pass	□NG ,		
9.Others:				
2 · Mechanical Specificati	on:			
1. PCB Size:	□Pass	□NG ,		
2.Frame Size :	□Pass	□NG ,		
3.Materal of Frame:	□Pass	□NG ,		
4.Connector Position:	□Pass	□NG ,		
5.Fix Hole Position:	□Pass	□NG ,		
6. Thickness of PCB:	□Pass	□NG ,		
7. Height of Frame to	□Pass	□NG ,		
PCB:				
8.Height of Module:	□Pass	□NG ,		
9.Others:	□Pass	□NG ,		
3 · Relative Hole Size :				
1.Pitch of Connector:	□Pass	□NG ,		
2.Hole size of	□Pass	□NG ,		
Connector:				
3.Mounting Hole size:	□Pass	□NG ,		
4.Mounting Hole Type:	□Pass	□NG ,		
5.Others:	□Pass	□NG ,		

>> Go to page 2 <<



Module Number :		Page: 2
4 · Electronic Characterist	ics of Modul	
1.Input Voltage:	□Pass	
2.Supply Current:	□Pass	□NG ,
3.Driving Voltage for	□Pass	□NG ,
OLED:	⊔Fa55	LING ,
4.Contrast for OLED:	□Pass	□NG ,
5.Negative Voltage Output:	□Pass	□NG ,
6.Interface Function:	□Pass	□NG ,
7.ESD test:	□Pass	□NG ,
8.Others:	□Pass	□NG ,
Sales signature:_		
paics signature		